

Growth, characterization and interfacial reaction of magnetron sputtered Pt/CeO₂ thin films on Si and Si₃N₄ substrates

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Abstract

Pt/CeO₂ thin films were deposited on Si and Si₃N₄ substrates by magnetron sputtering at room temperature. Growth of the films on Si and Si₃N₄ were characterized by XRD, FESEM and AFM. Interaction of Pt/CeO₂ films with Si in Si and Si₃N₄ substrates was extensively investigated by XPS. XRD studies show that films are oriented preferentially to (200) direction of CeO₂. XPS results show that Pt is mainly present in +2 oxidation state in Pt/CeO₂/Si film, whereas Pt⁴⁺ predominates in Pt/CeO₂/Si₃N₄ film. Ce is present as both +4 and +3 oxidation states in Pt/CeO₂ films deposited on both Si and Si₃N₄ substrates, but concentration of Ce³⁺ species is observed to be more in Pt/CeO₂/Si film. Interfacial reaction between CeO₂ and Si substrate is controlled in presence of Pt. Pt/Ce concentration ratio decreases in Pt/CeO₂/Si₃N₄ film upon successive sputtering, whereas this ratio decreases initially and then increases in Pt/CeO₂/Si film. Pt is segregated at the interface in Pt/CeO₂/Si film, whereas Pt is diffused outwards in Pt/CeO₂/Si₃N₄ film as observed from depth profiling studies.

Keywords: Thin films; Pt/CeO₂; Si and Si₃N₄ substrates; Interfacial reaction; XPS

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1. Introduction

Metal oxides are an important class of materials due to their potential applications in heterogeneous catalysis, photocatalysis, electrochemistry, sensors, solar cells and electronic devices [1–10]. Addition of a second metal into metal oxide matrix forming a mixed metal/metal oxide interface can exhibit interesting properties that are fundamentally different from those of respective metal oxides. In this sense, detailed understanding of metal/metal oxide interface is very crucial from fundamental view point.

CeO₂ has been extensively studied due to its various applications in last several years. It is an attractive material for various catalytic, electronic, optical, electrical, electrochemical, gas sensor and corrosion resistant applications [11–19]. In recent years, Pt/CeO₂ catalyst has widely been used in auto exhaust and fuel cell catalysis for its high activity [20,21]. Catalytic activity of Pt/CeO₂ is influenced by redox nature of CeO₂ as well as the synergistic effect between Pt and CeO₂. Pt/CeO₂ thin films show significant catalytic activity towards methanol electrooxidation and high activity in polymer electrolyte membrane fuel cell (PEMFC) as anode material [22]. Matolín et al. have demonstrated the presence of Pt²⁺ species in Pt/CeO₂ thin film grown on Si substrate, whereas both Pt²⁺ and Pt⁴⁺ species are observed in the same film grown on carbon nanotube [23]. This suggests that substrates influence the oxidation states and concentration of Pt species.

Pt/CeO₂ thin films have mainly been grown on Si, carbon nanotube, graphite foil, glassy carbon and glass substrates [22–28]. Significant works on the growth, structure and interfacial reaction between CeO₂ and different substrates have been in the literature [29–32]. Recently, we have investigated interfacial reactions between CeO₂ and substrates like Si, Al, Ti–6Al–4V alloy, Si₃N₄ and glass using XPS [30,31]. However, detailed studies on the nature of interaction

between Pt/CeO₂ thin film and different substrates and its influence on the electronic structure are limited in the literature. Moreover, growth and structure of Pt/CeO₂ on Si₃N₄ substrate and their interaction lack in the literature. In the present study, we report the growth of Pt/CeO₂ films on Si and Si₃N₄ substrates by magnetron sputtering. Structure, morphology and roughness of Pt/CeO₂ films are investigated by X-ray diffraction (XRD), field emission scanning electron microscopy (FESEM) and atomic force microscopy (AFM), respectively. X-ray photoelectron spectroscopy (XPS) studies have been carried out in details to understand the interfacial reaction between Pt/CeO₂ thin films and substrates.

2. Experimental methods

Pt/CeO₂ thin films were deposited on Si and Si₃N₄ substrates using a CeO₂ target (Allvac, 99.9%) and Pt foil (Arora Matthey, 99.9%) employing magnetron sputtering assisted by inductively coupled plasma generated with 50 W radio frequency (RF) power at 13.56 MHz. Pt foil was kept on the middle of the CeO₂ target. The substrates were cleaned with acetone/isopropyl alcohol by sonication prior to loading into the vacuum chamber. The chamber was pumped down to a base pressure of 3×10^{-6} mbar. The substrates were etched with H₂ plasma prior to deposition of thin films. Sputter deposition was carried out at room temperature with Ar atmosphere at a pressure of 8 μ bar. The substrate was biased to a constant negative voltage of 150 V, whereas the target was biased with bipolar pulses of 300 V using a pulse generator. Thickness of obtained Pt/CeO₂ thin films is 25 ± 1 nm.

The structure of Pt/CeO₂ films was determined by XRD employing a PANalytical X'Pert PRO X-Ray diffractometer operated with CuK α radiation of 1.5418 Å wavelength at 40 kV and 30 mA in the 2 θ range 20–80° in bulk mode. The surface morphology of thin films were examined by FESEM using a Carl Zeiss Supra 40. Detailed surface roughness was investigated

by AFM from CSEM Instruments (Model SSI) operated in non-contact mode. XPS of Pt/CeO₂ thin films were recorded with a SPECS spectrometer using non-monochromatic AlK α radiation (1486.6 eV) as an X-ray source operated at 150 W (12.5 kV and 12 mA). The binding energies reported here were calculated with reference to C1s peak at 284.6 eV. All the spectra were obtained with pass energy of 25 eV and step increment of 0.05 eV. Successive sputtering was carried out by defocused Ar⁺ ion beam using QE11/35 ion gun by applying energy of 1 keV with Ar gas pressure of 2×10^{-6} Torr for 3, 5, 5, 5, 5 and 5 min. Depth profile spectra were recorded with pass energy of 40 eV and step increment of 0.05 eV. The experimental data were curve fitted into several components with Gaussian–Lorentzian peaks after Shirley background subtraction employing CasaXPS program.

3. Results and discussion

Structural and morphological studies

XRD patterns of Pt/CeO₂ films deposited on Si and Si₃N₄ are shown in the range of 20–60° in Fig. 1. A broad peak at 33.2° noticed in both the films is indexed into CeO₂(200) reflection indicating the nanocrystalline nature of the films [33,34]. Presence of only (200) diffraction peak in Pt/CeO₂/Si film indicates that the film structure on Si substrate is orientated preferentially to (200) plane of CeO₂. On the other hand, in Pt/CeO₂ film deposited on Si₃N₄, low intense peaks at 28.5°, 47.5° and 56.3° associated with reflections from (111), (220) and (311) planes of CeO₂ are also observed along with intense peak at 33.2°. It is to be noted that peaks related to Pt metal, PtO or PtO₂ cannot be detected in both the films indicating that Pt is incorporated as ions into CeO₂ lattice which agrees well with works on Pt/CeO₂ catalysts done by Bera et al [20]. Grain sizes calculated from Debye-Scherrer method are 4.5 and 4.3 nm for Pt/CeO₂/Si and Pt/CeO₂/Si₃N₄, respectively.

Fig. 2 displays FESEM images of as-deposited Pt/CeO₂ films on Si and Si₃N₄ substrates. Micrographs show that obtained films have good adherence to the substrates. The surface of Pt/CeO₂ film deposited on Si substrate is very smooth and composed of very fine grains, whereas film coated on Si₃N₄ shows uniform morphology with large grain size. This can be due to the difference in roughness of the substrates.

Surface roughness of Pt/CeO₂ films has been obtained by AFM. The 3D AFM images of as-deposited Pt/CeO₂ thin films deposited on Si and Si₃N₄ substrates are shown in Fig. 3. Average roughness (R_a) and root mean square roughness (R_{rms}) values for Pt/CeO₂/Si are 0.35 and 0.48 nm, whereas those for Pt/CeO₂/Si₃N₄ are 3.53 and 4.47 nm, respectively. It can be seen that roughness of Pt/CeO₂ film on Si₃N₄ is more in comparison with that on Si substrate in as-deposited condition that can be due to the higher roughness of Si₃N₄ substrate.

XPS studies

Detailed XPS studies of Pt/CeO₂ thin films deposited on Si and Si₃N₄ substrates have been carried out to understand the interfacial reaction between Pt/CeO₂ films and these substrates. XPS of Pt/CeO₂/Si and Pt/CeO₂/Si₃N₄ films with Pt concentrations of 7 and 9 at.%, respectively are discussed here.

Pt4f core level spectra

XPS of Pt 4f core level in Pt/CeO₂ thin films deposited on Si and Si₃N₄ substrates are observed to be broad in nature indicating the presence of multiple oxidation states of Pt. In both Pt/CeO₂/Si and Pt/CeO₂/Si₃N₄ films, Pt4f spectra are resolved into sets of spin-orbit doublets and their curve fitted spectra are shown in Fig. 4. Accordingly, Pt4f_{7/2,5/2} peaks at 72.2, 75.5 and 74.4, 77.7 eV observed in Pt/CeO₂/Si thin film are assigned to Pt²⁺ and Pt⁴⁺, respectively [20,23]. Peaks at similar binding energies are also observed in Pt/CeO₂/Si₃N₄ film. However,

concentration of Pt^{2+} is observed to be more in the film deposited on Si substrate in relation to Si_3N_4 substrate. In $\text{Pt/CeO}_2/\text{Si}$ film, concentration of Pt^{2+} is 88%, whereas it is 47% in case of $\text{Pt/CeO}_2/\text{Si}_3\text{N}_4$ film. It is important to note that Pt metal peak is not observed in both the films indicating the Pt– CeO_2 interaction. This interaction results in the incorporation of Pt into Ce^{4+} sites in CeO_2 lattice as ions that agrees well the XRD studies demonstrating the absence of Pt metal peaks. Incorporation of Pt, Ru and In into CeO_2 has been reported in the literature [20,34–36]. Matolín et al. have shown the presence of different amount of Pt^{2+} and Pt^{4+} in Pt/CeO_2 thin films deposited on different substrates [23–25,27].

Ce3d core level spectra

Spectral nature of the Pt/CeO_2 film deposited on Si and Si_3N_4 substrates indicate that Ce is in both +4 and +3 oxidation states and it can be resolved into several $\text{Ce}3d_{5/2,3/2}$ spin-orbit doublet peaks. In Fig. 5, curve fitted Ce3d core level spectra of Pt/CeO_2 thin films coated on Si and Si_3N_4 substrates are presented. In these figures, peaks labeled as v correspond to $3d_{5/2}$ photoemissions, whereas u peaks are related to $3d_{3/2}$ photoemissions. In Ce3d spectrum of $\text{Pt/CeO}_2/\text{Si}$ film of Fig. 5, v''' and u''' spin-orbit peaks at 897.9 and 916.4 eV, respectively with 18.5 eV separation are assigned for the primary photoionization from Ce^{4+} with $\text{Ce}3d^94f^0\text{O}2p^6$ final state. Lower binding energy states of $v''-u''$ (888.5 and 907.0 eV) and $v-u$ (882.5 and 900.9 eV) have been assigned to the shake-down satellite features of $\text{Ce}3d^94f^1\text{O}2p^5$ and $\text{Ce}3d^94f^2\text{O}2p^4$ final states, respectively [37–39]. Satellite peaks are associated with the charge transfer from ligand ($\text{O}2p$) to metal ($\text{Ce}4f$) during primary photoionization processes. Peaks labeled as v_o , u_o and v' , u' at 881.7, 899.1 and 885.3, 903.4 eV, respectively are associated with Ce^{3+} final states. It is to be noted that $v'-u'$ spin orbit doublet peaks correspond to main photoionization from $\text{Ce}3d^94f^1\text{O}2p^6$ final state, whereas lower binding energy v_o-u_o peaks are attributed to

characteristic shake-down satellites of $\text{Ce}3d^{9/2}4f^{2/2}O2p^5$ final state [38–40]. It is clear from Fig. 5 that the intensities of Ce^{4+} and Ce^{3+} peaks for Pt/CeO₂ film deposited on Si₃N₄ substrate are different from Pt/CeO₂/Si film. Binding energies and relative integrated peak areas of Ce3d_{5/2,3/2} spin-orbit doublets in Pt/CeO₂ films deposited on Si and Si₃N₄ substrates are summarized in Tables 1 and 2, respectively. Peak areas of Ce^{4+} and Ce^{3+} components are commonly used to estimate their relative concentrations in the films. Concentration of Ce^{4+} in Pt/CeO₂ deposited on Si is estimated to be 77% with respect to the total amount of Ce species indicating the presence of significant amount of Ce^{3+} species. On the other hand, concentration of Ce^{4+} is 83% in Pt/CeO₂ deposited on Si₃N₄ substrate. However, amount of Ce^{3+} is less in Pt/CeO₂/Si film in the present study compared to CeO₂/Si film as demonstrated by our earlier work, whereas Ce^{3+} concentration is more in Pt/CeO₂/Si₃N₄ film in relation to CeO₂/Si₃N₄ [30]. Concentrations of Ce^{4+} and Ce^{3+} in Pt/CeO₂ and CeO₂ films deposited on Si and Si₃N₄ substrates are given in Table 3. It has been shown in our previous study that there is a limited interfacial reaction between CeO₂ and Si when CeO₂ is deposited on Si₃N₄ substrate [30]. In the present work, lower concentration of Ce^{3+} in Pt/CeO₂/Si film compared to CeO₂/Si film indicates that extent of interfacial reaction between CeO₂ and Si by means of reduction of Ce^{4+} to Ce^{3+} is less in Pt/CeO₂ thin film deposited on Si substrate.

O1s core level spectra

Oxidation states of Ce in Pt/CeO₂/Si and Pt/CeO₂/Si₃N₄ films can also be evaluated from respective O1s core level spectrum. Curve fitted O1s core level spectra from as-deposited Pt/CeO₂/Si and Pt/CeO₂/Si₃N₄ films are shown in Fig. 6. Curve fitted O1s core level spectrum in Pt/CeO₂ film on Si contains four component peaks at 529.9, 531.6, 532.6 and 533.6 eV. Peak at 529.9 eV is related to O²⁻ species in CeO₂, whereas peak at 532.6 eV is associated with O in

Si–O bonded species that agrees well with the literature [32,41]. Intermediate peak at 531.6 eV corresponds to Ce^{3+} species originated from silicate or Ce_2O_3 species [32]. Areas under O1s component peaks associated with Ce^{4+} and Ce^{3+} species provide their individual concentrations. It has been estimated that 26% Ce^{3+} species is observed to be present in Pt/CeO₂/Si film which is close to the value obtained from corresponding Ce3d peak. A weak higher binding energy component peak at 533.6 eV is assigned for adsorbed H₂O species [42]. In contrast, an intense peak at 529.9 eV in O1s core level spectrum is observed in Pt/CeO₂/Si₃N₄ film that corresponds to O^{2-} species in CeO₂. Two low intense component peaks at 531.5 and 532.5 eV stand for oxygen species in silicate or Ce_2O_3 and Si–O network, respectively. Thus, O1s core levels demonstrate that the relative concentration of Ce^{3+} related oxygen species is highest in the CeO₂/Si film compared to Si₃N₄ substrate.

Si2p core level spectra

Core level Si2p spectra of Si and Si₃N₄ substrates coated with Pt/CeO₂ films are shown in Fig. 7. Broad envelop of Si2p core level spectrum in Pt/CeO₂/Si indicates the presence of several Si species that can be resolved into component peaks. A peak at 99.2 eV is associated with elemental Si present in Si substrate, whereas peaks observed at 101.1 and 102.6 eV correspond to Si^{2+} and Si^{3+} species [43,44]. The presence of these species at the interface of Pt/CeO₂ and Si shows the interaction between them where it can be expected to bond in a Si–Ce–O matrix in the form of silicate [41,45]. On the other hand, a single peak at 101.6 eV in Si2p core level spectrum in Pt/CeO₂/Si₃N₄ film is attributed to Si–N bond in Si₃N₄ [46]. It is to be noted that observation of substrate core level signal in these films of 25 nm thickness, especially in the case of reactive substrate like Si indicates the intermixing of Pt/CeO₂ film and Si. Little interfacial reaction occurs in the case of Si₃N₄ substrate as evident from the very weak substrate signal.

Depth profile studies

In order to get the electronic structure and compositions of underneath layers, Pt/CeO₂ films deposited on Si and Si₃N₄ substrates have been mildly sputtered up to few layers and their compositions as well as elemental oxidation states in each interior layers have been analyzed by XPS. Core level spectra of Pt4f and Ce3d of Pt/CeO₂/Si and Pt/CeO₂/Si₃N₄ thin films at different stages of sputtering are shown in Fig. 8. Ratios of C_{Pt}/C_{Si} , C_{Ce}/C_{Si} and C_{Pt}/C_{Ce} obtained from depth profiles of Pt/CeO₂/Si and Pt/CeO₂/Si₃N₄ films are displayed in Fig. 9. It has been noticed that concentrations of both Pt and Ce get reduced in relation to Si in Pt/CeO₂/Si and Pt/CeO₂/Si₃N₄ thin films upon sputtering. In both the cases, films grow layer by layer fashion on the substrates as seen from variation of Pt/Si and Ce/Si concentration ratios with sputtering. However, C_{Pt}/C_{Ce} ratio shows a different behavior at different stages of sputtering. In case of Pt/CeO₂/Si film, the ratio has been observed to decrease up to certain layer and then it increases, whereas it decreases monotonically in Pt/CeO₂/Si₃N₄ film. In Pt/CeO₂/Si film, Pt appears to segregate at the interface of Si substrate and film as observed from the C_{Pt}/C_{Ce} ratio in depth profile. In contrast, Pt seems to be diffused outward in case of Pt/CeO₂/Si₃N₄ film.

In the present study, there is no diffraction peak related to Pt metal or its oxides in the XRD patterns of Pt/CeO₂ films deposited on Si and Si₃N₄. XPS studies of these films demonstrate that Pt is present as Pt²⁺ and Pt⁴⁺ oxidation states in the films indicating the incorporation of Pt into CeO₂ matrix that supports XRD results. Our previous studies have shown the significant reduction of Ce⁴⁺ in CeO₂ into Ce³⁺ in CeO₂/Si film while the reduction is nearly controlled in CeO₂/Si₃N₄ film [30]. In the present work, extent of interaction between CeO₂ and Si is less in Pt/CeO₂/Si film compared to CeO₂/Si film that can be seen in Table 3. Concentration of Ce³⁺ is 32% in CeO₂/Si film, whereas it is 23% in Pt/CeO₂/Si film. It has also

been noticed that concentration of Pt^{2+} is more in Pt/CeO₂/Si film in relation to Pt/CeO₂/Si₃N₄ film. Stabilization of Pt^{2+} and Pt^{4+} ions in CeO₂ matrix and difference in extent of interfacial reaction can be substantiated from the relative positions of valence bands. Pt metal has high electron density at the Fermi level (E_F) and its valence band extend even up to 6 eV below E_F . On the other hand, valence bands of Si⁰, Ce⁴⁺4f and Si₃N₄ are 1.1, 2 and 5.1 eV, respectively with respect to Fermi level [12,47,48]. Therefore, Pt can transfer its electrons easily to Ce⁴⁺ that facilitates conversion of Ce⁴⁺ to Ce³⁺ to a certain extent and Pt itself can be oxidized to form Pt^{2+} and Pt^{4+} . Again, Pt can also give electrons to Si⁰ that can sluggish the interaction between CeO₂ and Si. Therefore, internal electron transfer among Pt, CeO₂ and Si results in the formation of Pt^{2+} and Pt^{4+} in Pt/CeO₂/Si film. In contrast, this type of electron transfer cannot be facilitated in Pt/CeO₂/Si₃N₄ film as valence band level of Si₃N₄ is located in lower energy side in relation to Pt⁰ and Ce⁴⁺ according to the Fermi level. Moreover, Si₃N₄ is an inert substrate as it has filled p levels of Si. In this sense, synergistic interaction mainly occurs between Pt and CeO₂ in Pt/CeO₂/Si₃N₄ film. Here, Pt transfers its electrons to CeO₂ only leading to the formation of more Pt^{4+} species. Therefore, concentration of Ce³⁺ species is observed to be more in Pt/CeO₂/Si₃N₄ film compared to CeO₂/Si₃N₄ film. It is important to note that there can be a possibility of formation of platinum silicide phase in Pt/CeO₂/Si film thermodynamically at room temperature [49,50]. However, in the present study, platinum silicide formation has not been observed as evident from core level binding energy of Si2p core level.

4. Conclusions

Pt/CeO₂ films were deposited on Si and Si₃N₄ substrates by magnetron sputtering. XRD patterns confirm the presence of nanocrystalline CeO₂ phase on Si and Si₃N₄ substrates. XPS studies show the presence of Pt^{2+} as predominant species in Pt/CeO₂/Si film, whereas Pt^{4+}

concentration is observed to be more in Pt/CeO₂/Si₃N₄ film. There is no signature of Pt metal peak in XRD patterns indicating the incorporation of Pt into CeO₂ lattice as ions. Extent of interaction between CeO₂ and Si is less in presence of Pt in Pt/CeO₂/Si film. Depth profiling studies show that Pt is segregating at the Si/film interface in Pt/CeO₂/Si film and Pt is diffusing outwards in Pt/CeO₂/Si₃N₄ film.

Acknowledgments

Authors would like to thank the Director, CSIR–National Aerospace Laboratories for giving permission to publish this work. Authors wish to acknowledge Mr. Siju and Mr. Praveen for carrying out FESEM and AFM measurements, respectively.

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Table 1. Binding energies, FWHMs and integrated peak areas of Ce3d_{5/2,3/2} spin-orbit doublets in Pt/CeO₂ film deposited on Si.

Peak assignment	Ce species	Binding energy peak (eV)	Relative area (%)
v ₀	Ce ³⁺	881.7	6
v	Ce ⁴⁺	882.5	13
v'	Ce ³⁺	885.3	8
v''	Ce ⁴⁺	888.5	13
v'''	Ce ⁴⁺	897.9	16
u ₀	Ce ³⁺	899.1	4
u	Ce ⁴⁺	900.9	10
u'	Ce ³⁺	903.4	5
u''	Ce ⁴⁺	907.0	11
u'''	Ce ⁴⁺	916.4	14

Table 2. Binding energies, FWHMs and integrated peak areas of Ce3d_{5/2,3/2} spin-orbit doublets in Pt/CeO₂ film deposited on Si₃N₄.

Peak assignment	Ce species	Binding energy peak (eV)	Relative area (%)
v ₀	Ce ³⁺	881.7	4
v	Ce ⁴⁺	882.6	14
v'	Ce ³⁺	885.2	6
v''	Ce ⁴⁺	888.3	16
v'''	Ce ⁴⁺	897.9	17
u ₀	Ce ³⁺	899.2	3
u	Ce ⁴⁺	901.0	11
u'	Ce ³⁺	903.3	4
u''	Ce ⁴⁺	907.2	12
u'''	Ce ⁴⁺	916.4	13

Table 3. Relative surface concentrations of Ce^{4+} and Ce^{3+} components evaluated from XPS in Pt/CeO₂ and CeO₂ thin films deposited on Si and Si₃N₄ substrates.

Thin films	Ce^{4+}	Ce^{3+}
Pt/CeO ₂ /Si	77	23
CeO ₂ /Si	68	32
Pt/CeO ₂ / Si ₃ N ₄	83	17
CeO ₂ /Si ₃ N ₄	89	11

Figure captions

Fig. 1. XRD patterns of Pt/CeO₂ thin films deposited on (a) Si and (b) Si₃N₄ substrates.

Fig. 2. FESEM images of Pt/CeO₂ thin films deposited on (a) Si and (b) Si₃N₄ substrates.

Fig. 3. AFM images of Pt/CeO₂ thin films deposited on (a) Si and (b) Si₃N₄ substrates.

Fig. 4. Curve fitted XPS of Pt4f core levels of Pt/CeO₂ thin films deposited on (a) Si and (b) Si₃N₄ substrates.

Fig. 5. Curve fitted XPS of Ce3d core levels of Pt/CeO₂ thin films deposited on Si and Si₃N₄ substrates.

Fig. 6. Curve fitted XPS of O1s core levels in as-deposited Pt/CeO₂ thin films on (a) Si and (b) Si₃N₄ substrates.

Fig. 7. Curve fitted XPS of Si2p core levels of Pt/CeO₂ thin films deposited on Si and Si₃N₄ substrates.

Fig. 8. XPS of Ce3d and Pt4f core levels of Pt/CeO₂/Si (top) and Pt/CeO₂/Si₃N₄ (bottom) thin films with different stages of sputtering: (a) as-deposited, (b) 3 min, (c) 8 min, (d) 13 min, (e) 18 min, (f) 23 min and (g) 28 min.

Fig. 9. C_{Pt}/C_{Si}, C_{Ce}/C_{Si} and C_{Pt}/C_{Ce} ratios in Pt/CeO₂/Si and Pt/CeO₂/Si₃N₄ films as function of sputtering time.

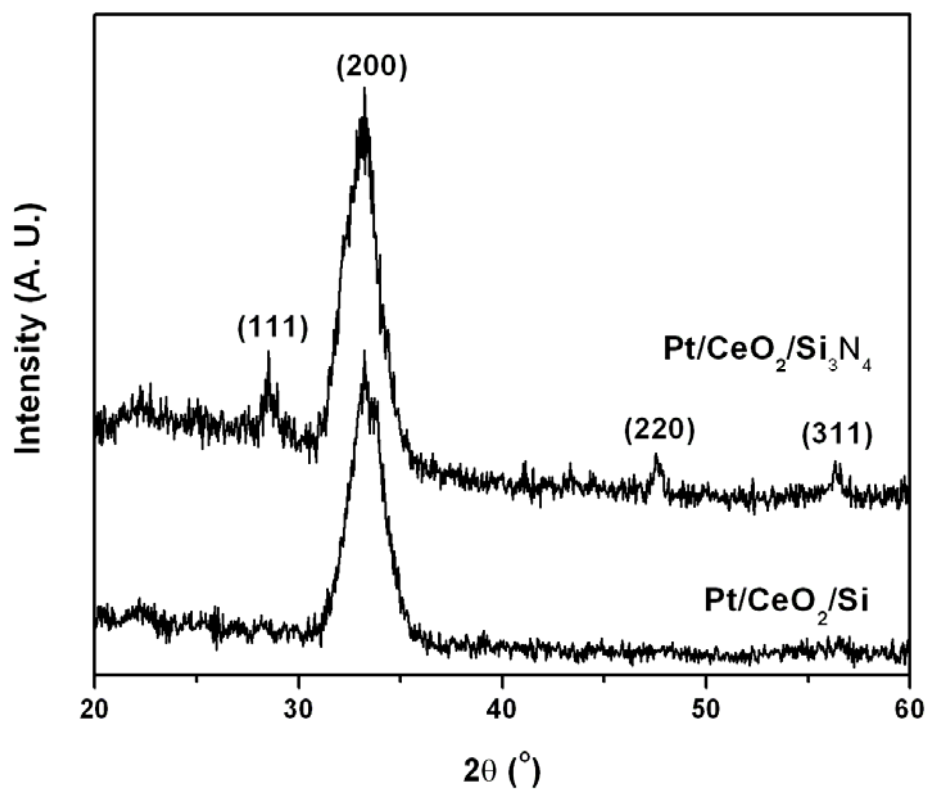
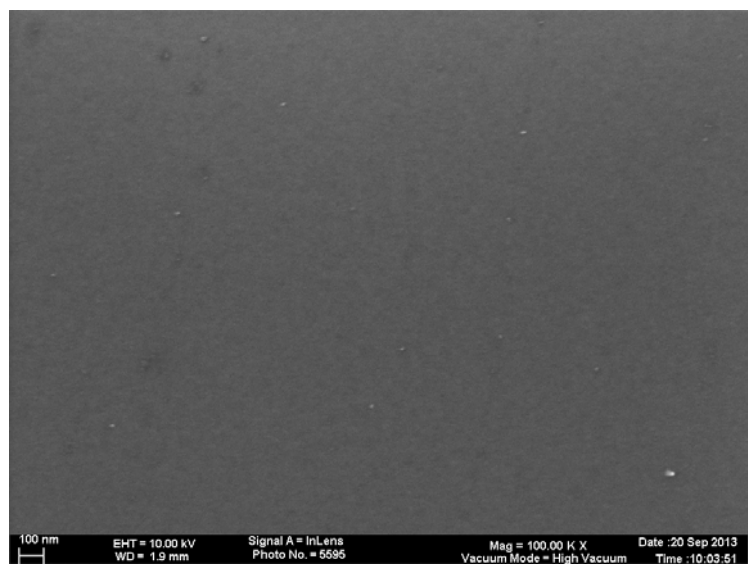
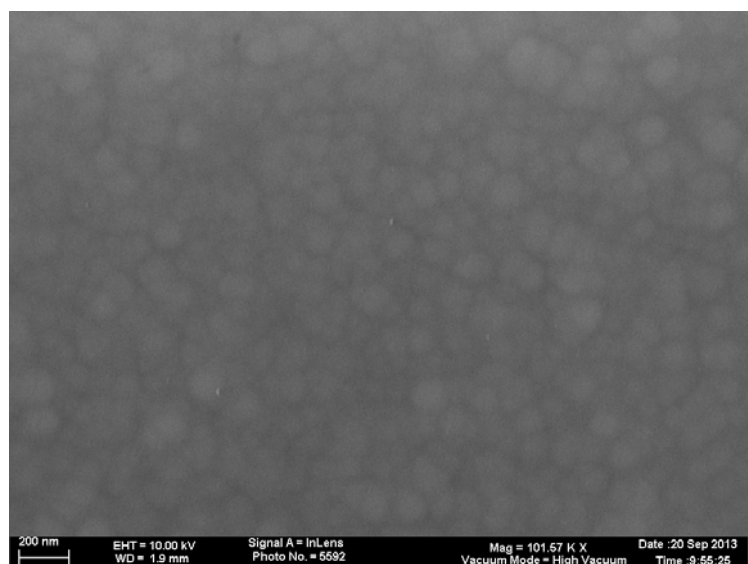


Fig. 1. XRD patterns of $\text{Pt/CeO}_2/\text{Si}$ and $\text{Pt/CeO}_2/\text{Si}_3\text{N}_4$ thin films.

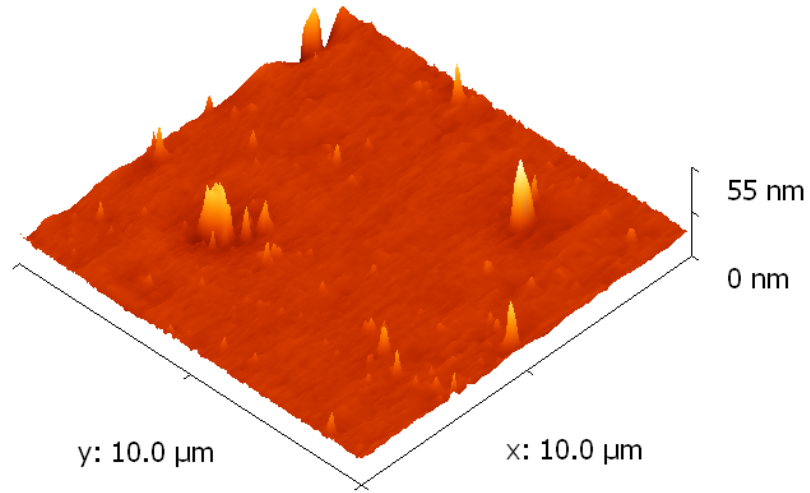


Pt/CeO₂/Si

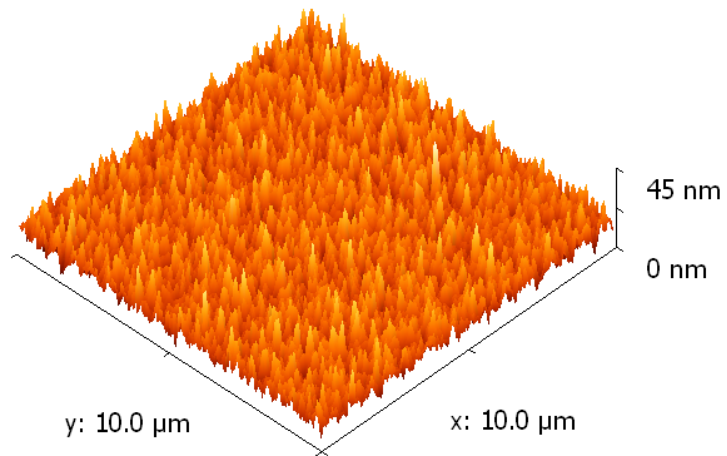


Pt/CeO₂/Si₃N₄

Fig. 2. FESEM images of Pt/CeO₂/Si and Pt/CeO₂/Si₃N₄ thin films.



Pt/CeO₂/Si



Pt/CeO₂/Si₃N₄

Fig. 3. AFM images of Pt/CeO₂/Si and Pt/CeO₂/Si₃N₄ thin films.

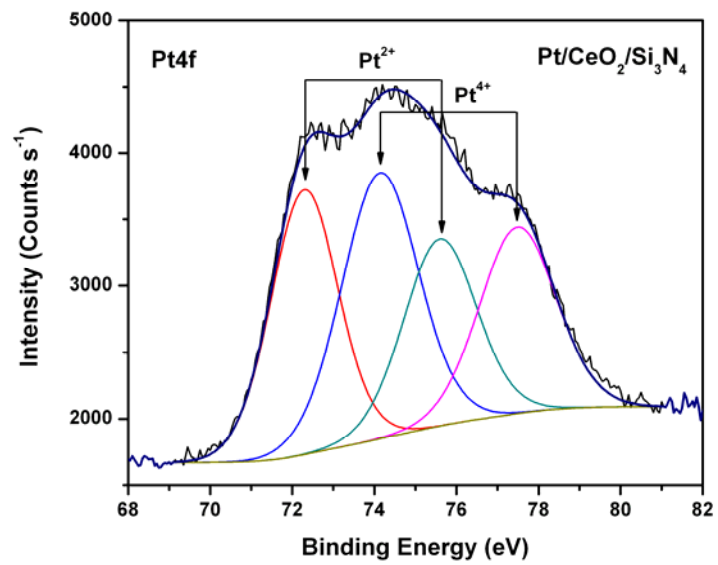
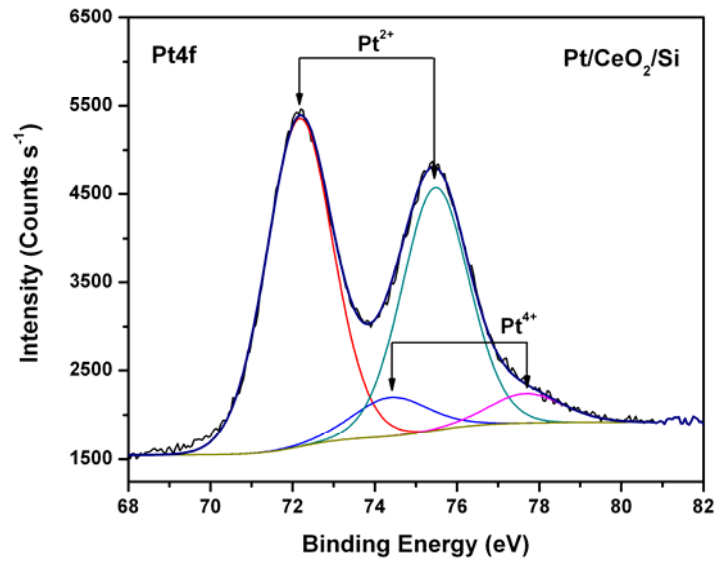


Fig. 4. Curve fitted XPS of Pt4f core levels of Pt/CeO₂/Si and Pt/CeO₂/Si₃N₄ thin films.

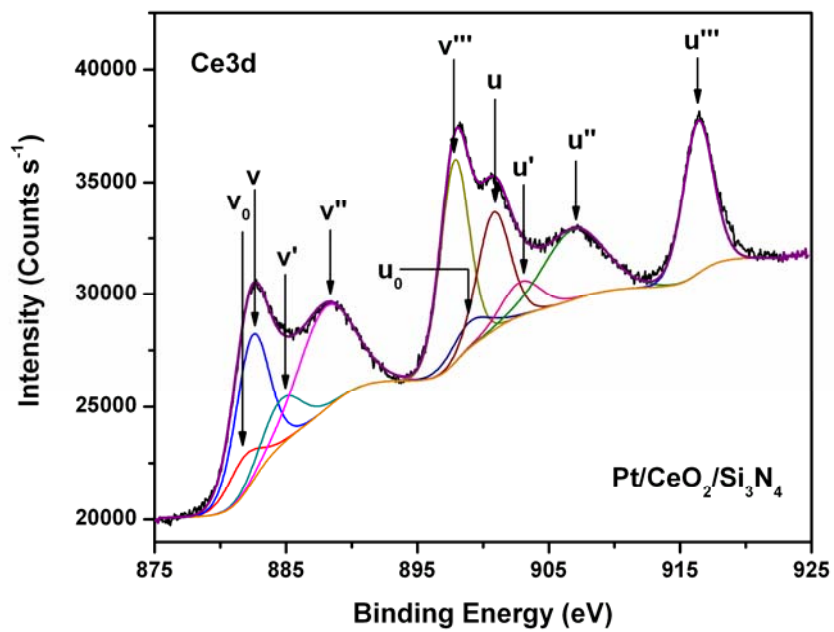
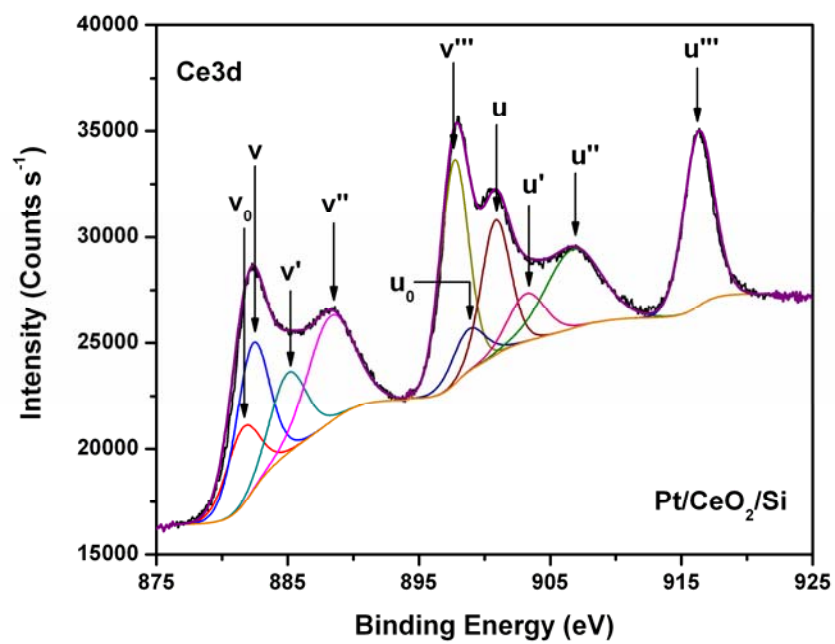


Fig. 5. Curve fitted XPS of Ce3d core levels of Pt/CeO₂/Si and Pt/CeO₂/Si₃N₄ thin films.

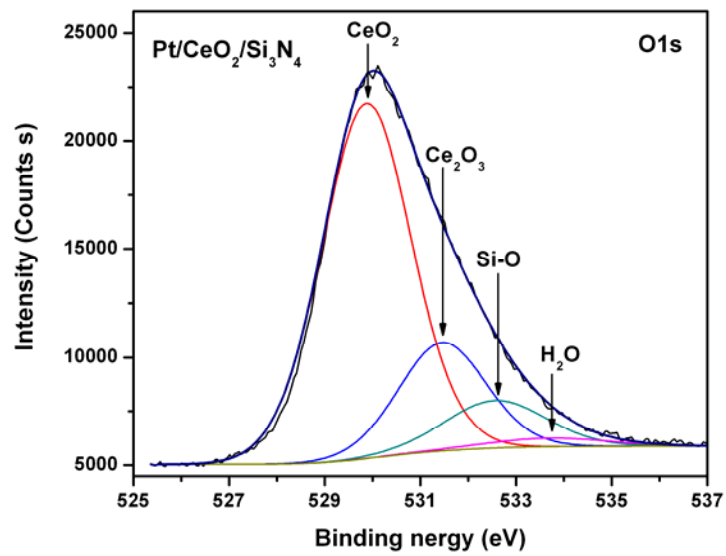
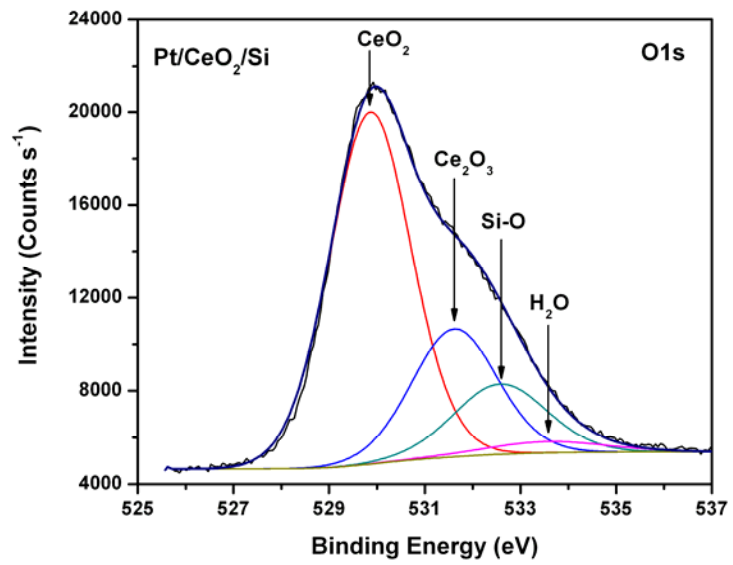


Fig. 6. Curve fitted XPS of O1s core levels in Pt/CeO₂/Si and Pt/CeO₂/Si₃N₄ thin films.

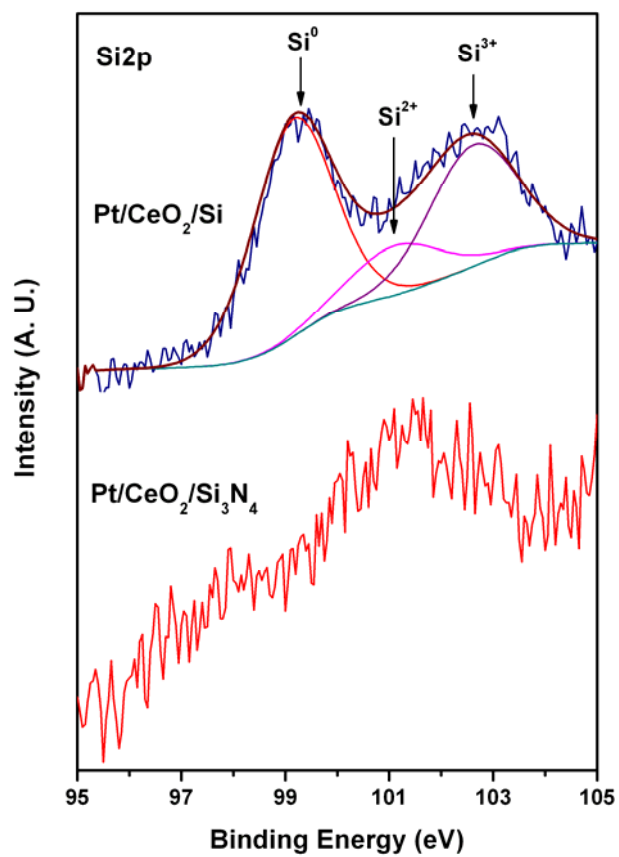


Fig. 7. Curve fitted XPS of Si2p core levels of Pt/CeO₂/Si and Pt/CeO₂/Si₃N₄ thin films.

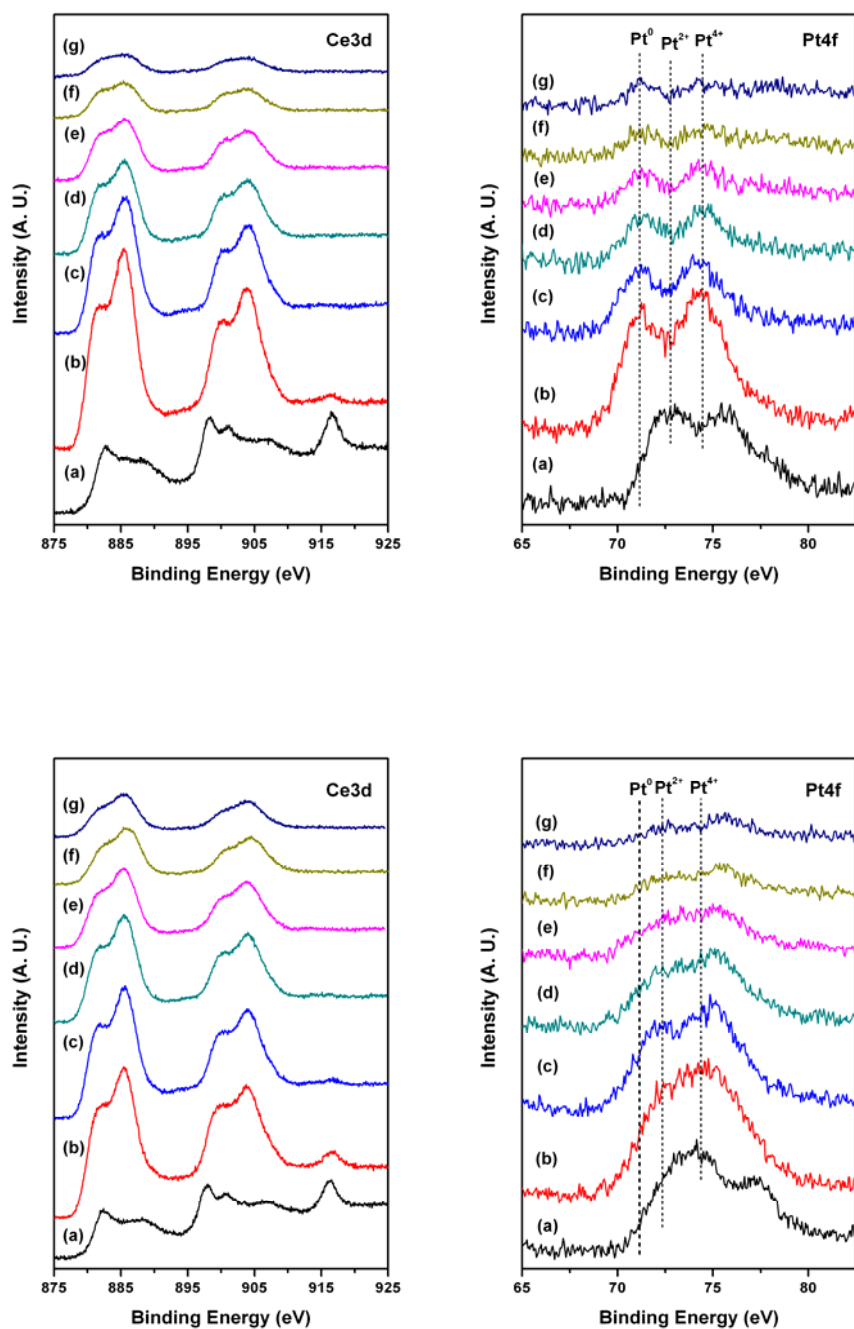


Fig. 8. XPS of Ce3d and Pt4f core levels of Pt/CeO₂/Si (top) and Pt/CeO₂/Si₃N₄ (bottom) thin films with different stages of sputtering: (a) as-deposited, (b) 3 min, (c) 8 min, (d) 13 min, (e) 18 min, (f) 23 min and (g) 28 min.

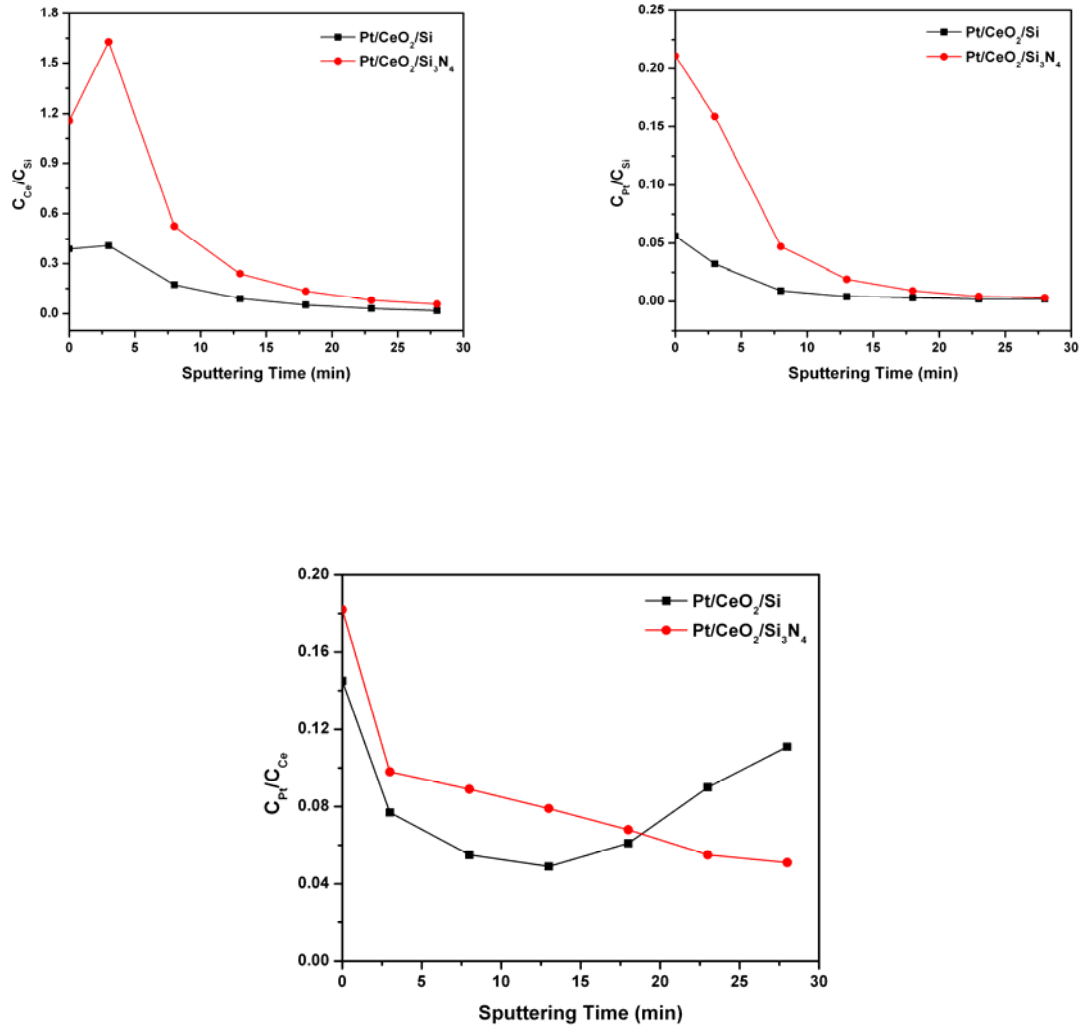


Fig. 9. C_{Pt}/C_{Si} , C_{Ce}/C_{Si} and C_{Pt}/C_{Ce} ratios in Pt/CeO₂/Si and Pt/CeO₂/Si₃N₄ films as function of sputtering time.